

Specifications	Details
Material types	FR-1, FR-4, CEM-1, aluminum clad
Material thickness	0.4, 0.6, 0.8, 1.0, 1.2, 1.6, 2.0mm
Layer count	1 to 32 layers
Max board size	23.00 x 35.00" (580*900mm)
IPC class	Class II, class 1
Annular ring	5mil/side or greater (minimum design)
Finish plating	Solder (HASL), lead-free solder (HASL), ENIG (electroless nickel immersion gold), OSP, immersion silver, immersion tin, immersion nickel, hard gold
Copper weight	0.5-2oz
Trace/space width	3mil or greater
Drill clearance	0.1mm (laser drilling)
Plated slots	0.036 or greater
Smallest hole (finish)	0.1mm or greater
Gold fingers	1 to 4 edge (30 to 50-micron gold)
SMD pitch	0.080-0.020- 0.010"
Solder mask type	LPI glossy, LPI-matte, SR1000
Solder mask colors	Green, red, blue, black, white and yellow
Legend colors	White, yellow, black, red and blue
CNC route point	Any
Minimum route width	0.031"
Scoring	Straight lines, jump scoring, panel edge-to-edge, CNC
Body gold	Hard*, immersion* (up to 50-micron gold)
Data file formats	Gerber 274x with embedded aperture
FAB drawing formats	DXF, HPGL, DWG, PDF
ET testing	Flying probe, single sided, 1 up the plate, clamp shell, Netlist
Countersink/counter bore	Available up to 0.250 diameter
Control impedance	Yes
Blind/buried vias	Yes
Peelable mask	Yes
Carbon	Yes